STRIVE FOR EXCELLENCE

Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: *Required Field*	

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-04-14
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by
MDF Champion
Date: 2025.04.14
11:21:17 CEST

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H755XIH3	2KCV*450XXXV	A	9991	2025-04-14
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	623	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Not Applicable	NAC	SACN305	
Package designator	Package size	Number of instances	Shape	
BGA	14x14	265	Bulk solder	
Comment	Package : A07U TFBGA 14X14X1.2 P 0.8 240+25L DM00221013			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	**Description**	
,		

QueryList : REACH-21st January 2025				**Response**
QUERY				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**2KCV*450XXXV**		623.4800		6000000.0	1000000.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	16.980	mg	supplier	die	Silicon (Si)	7440-21-3		16.238	mg	956302	26044.14
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	5183	141.14
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	16254	442.68
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	59	1.60
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	2650	72.18
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	471	12.83
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	59	1.60
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	19022	518.06
Substrate (A28404)	Copper & its alloys	149.963	mg	supplier	Substrate	Thermosetting resin (Including filler)	Proprietary		53.372	mg	355900	85603.12
				supplier	Substrate	Glass cloth	65997-17-3		32.617	mg	217500	52314.35
				supplier	Substrate	Copper foil	7440-50-8		12.702	mg	84700	20372.53
				supplier	Substrate	Gold (Au)	7440-57-5		0.780	mg	5200	1250.73
				supplier	Substrate	Copper (Cu)	7440-50-8		39.995	mg	266700	64148.22
				supplier	Substrate	Morpholine derivative	Proprietary		0.420	mg	2800	673.47
				supplier	Substrate	Barium Sulfate	7727-43-7		4.829	mg	32200	7744.93
				supplier	Substrate	Silica	7631-86-9		0.105	mg	700	168.37
				supplier	Substrate	Talc	14807-96-6		0.420	mg	2800	673.47
				supplier	Substrate	Dipropylene Glycol Monomethyl Ether	34590-94-8		2.519	mg	16800	4040.83
				supplier	Substrate	Epoxy Resin	85954-11-6		2.204	mg	14700	3535.73
DAF (ATB-125-12)	Precious metals	5.910	mg	supplier	Glue or tape	Butadiene, acrylonitrile polymer, carboxy-terminat	68610-41-3		3.842	mg	650000	6161.38
				supplier	Glue or tape	Formaldehyde, polymer with (chloromethyl)oxiran	37382-79-9		1.478	mg	250000	2369.76
				supplier	Glue or tape	Dapsone	80-08-0		0.355	mg	60000	568.74
				supplier	Glue or tape	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.118	mg	20000	189.58
				supplier	Glue or tape	Reaction product: bisphenol-A-(epichlorhydrin); e	25068-38-6		0.118	mg	20000	189.58
Bonding wires (Cu)	Precious metals	3.401	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		3.284	mg	965500	5266.67
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.105	mg	31000	169.10
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.012	mg	3500	19.09
Encapsulation (KE-G1250AAS)	Other inorganic materials	412.689	mg	supplier	Molding Compound	Silica(Fused)	60676-86-0		371.420	mg	900000	595720.95
				supplier	Molding Compound	Epoxy resin	Proprietary		21.873	mg	53000	35081.35
				supplier	Molding Compound	Phenol resin	Proprietary		17.746	mg	43000	28462.22
				supplier	Molding Compound	Carbon Black	1333-86-4		1.651	mg	4000	2647.65
Solder Balls (SACN305)	Other Nonferrous metals & alloys	34.537	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		33.311	mg	964500	53427.43
				supplier	Matte Sn	Silver (Ag)	7440-22-4		1.036	mg	30000	1661.82
				supplier	Matte Sn	Copper (Cu)	7440-50-8		0.173	mg	5000	276.97
				supplier	Matte Sn	Nickel(Ni)	7440-02-0		0.017	mg	500	27.70